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PRODUCT SPECIFICATION

Tentative Specification
 Preliminary Specification
 Approval Specification

MODEL NO.: V420H2 SUFFIX: PE5

Customer:

APPROVED BY

SIGNATURE

Name / Title

Note

(Ver. C1)

Please return 1 copy for your confirmation with your signature and comments.

Approved By	Checked By	Prepared By
Chao-Chun Chung	Ken Wu	Peggi Chiu

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PRODUCT SPECIFICATION

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PRODUCT SPECIFICATION

REVISION HISTORY

Version	Date	Page(New)	Section	Description
Ver. 2.0	18, Jan, 2011	All	All	The specification was first issued.

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Date : 18 Jan 2011

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PRODUCT SPECIFICATION

1. GENERAL DESCRIPTION

1.1 OVERVIEW

V420H2-PE5 is a 42" TFT Liquid Crystal Display product with driver ICs and 2ch-LVDS interface. This product supports 1920 x 1080 Full HDTV format and can display 16. 7M (8-bit) colors.

1.2 FEATURES

CHARACTERISTICS ITEMS	SPECIFICATIONS
Screen Diagonal [in]	42.02
Pixels [lines]	1920 × 1080
Active Area [mm]	930.24(H) × 523.26(V) (42" diagonal)
Sub-Pixel Pitch [mm]	0.1615(H) × 0.4845(V)
Pixel Arrangement	RGB vertical stripe
Weight [g]	TYP. 2155 g
Physical Size [mm]	965.24(W) × 566.51(H) × 1.75(D) Typ.
Display Mode	Transmissive mode / Normallly black
Contrast Ratio	3000:1 Тур.
	(Typical value measure at CMI's module)
Glass thickness (Array / CF) [mm]	0.7 / 0.7
Viewing Angle (CR>20)	+88/-88(H), +88/-88(V) Typ. (CR≧20)
	(Typical value measure at CMI's module)
Color Chromaticity	R=(0.658, 0.324)
	G=(0.257, 0.593)
	B=(0.135,0.096)
	W=(0.295, 0.337)
	(Light source is the standard light source "C" which is defined by
	CIE and driving voltages are based on suitable gamma
	voltages.)
Cell Transparency [%]	4.8%
Polarizer Surface Treatment	Anti-Glare coating (Haze 11%), Hard coating (3H)

1.3 MECHANICAL SPECIFICATIONS

Item	Min.	Тур.	Max.	Unit	Note
Weight	2105	2155	2205	g	-
I/F connector mounting position	The mounting incli screen center with	nation of the connoise in ± 0.5mm as the	ector makes the horizontal.		(2)

Note (1) Please refer to the attached drawings for more information of front and back outline dimensions.

Note (2) Connector mounting position

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2. ABSOLUTE MAXIMUM RATINGS

2.1 ABSOLUTE RATINGS OF ENVIRONMENT

Item	Symbol	Va	lue	Unit	Note	
nem	Symbol	Min.	Max.	Unit	Note	
Storage Temperature	T _{ST}	-20	+60	°C	(1)	
Operating Ambient Temperature	T _{OP}	0	+50	°C	(1), (2)	
Vibration (Non-Operating)	V _{NOP}	-	1.0	G	(3), (4)	

Note (1) Temperature and relative humidity range is shown in the figure below.

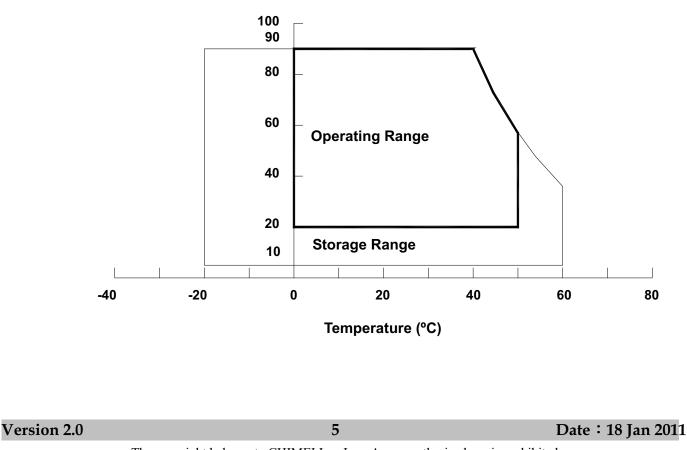
(a) 90 %RH Max. (Ta \leq 40 °C).

(b) Wet-bulb temperature should be 39 °C Max. (Ta > 40 °C).

- (c) No condensation.
- Note (2) The maximum operating temperature is based on the test condition that the surface temperature of display area is less than or equal to 65 °C with LCD module alone in a temperature controlled chamber. Thermal management should be considered in final product design to prevent the surface temperature of display area from being over 65 °C. The range of operating temperature may degrade in case of improper thermal management in final product design.

Note (3) 10 ~ 200 Hz, 10 min, 1 time each X, Y, Z.

Note (4) At testing Vibration and Shock, the fixture in holding the module has to be hard and rigid enough so that the module would not be twisted or bent by the fixture.



Relative Humidity (%RH)

One step solution for LCD / PDP / OLED panel application: Datasheet, inventory and accessory! www.panelook.com

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2.2 PACKAGE STORAGE

When storing modules as spares for a long time, the following precaution is necessary.

(a) Do not leave the module in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35° C at normal humidity without condensation.

(b)The module shall be stored in dark place. Do not store the TFT-LCD module in direct sunlight or fluorescent light.

2.3 ELECTRICAL ABSOLUTE RATINGS

2.3.1 TFT LCD MODULE

Itom	Symbol Value		Unit	Note	
Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	Vcc	-0.3	13.5	V	
Logic Input Voltage	VIN	-0.3	3.6	V	

2.3.2 BACKLIGHT CONVERTER UNIT

Item	Symbol	Val	lue	Unit	Note	
nem	Symbol	Min.	Max.	Unit	Note	
Lamp Voltage	VW	-	3000	VRMS		
Power Supply Voltage	VBL	0	30	V	(1)	
Control Signal Level	_	-0.3	7	V	(1), (3)	

Note (1) Permanent damage to the device may occur if maximum values are exceeded. Functional operation should be restricted to the conditions described under normal operating conditions.

Note (2) No moisture condensation or freezing.

Note (3) The control signals include On/Off Control and Internal PWM Control.

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3. ELECTRICAL CHARACTERISTICS

3.1 TFT LCD MODULE

Ta = 25 ± 2 °C

Parameter		Symbol		Value		l la it	Nata
		Symbol	Min.	Тур.	Max.	Unit	Note
Power Suppl	y Voltage	V _{cc}	10.8	12	13.2	V	(1)
Rush Curren	t	I _{RUSH}	-	-	3.2	А	(2)
	White Pattern	-	-	9.36	11.23	W	
Power Consumptior	Horizontal Stripe	-	_	10.56	14.28	W	(3)
	Black Pattern	-	-	5.16	6.24	W	
Damas	White Pattern			0.78	0.93	А	
Power Supply	Horizontal Stripe			0.88	1.19	A	(4)
Current	Black Pattern			0.43	0.52	А	
	Differential Input High Threshold Voltage	V _{lvth}	+100		_	mV	
	Differential Input Low Threshold Voltage	V _{LVTL}		-	-100	mV	
interface	Common Input Voltage	V _{CM}	1.0	1.2	1.4	V	(5)
	Differential input voltage	V _{ID}	200	-	600	mV	
	Terminating Resistor	R _T	-	100	-	ohm	
CMOS	Input High Threshold Voltage	V _{IH}	2.7	-	3.3	V	
interface	Input Low Threshold Voltage	V _{IL}	0	-	0.7	V	

Note (1) The module should be always operated within above ranges.

Note (2) Measurement Conditions:

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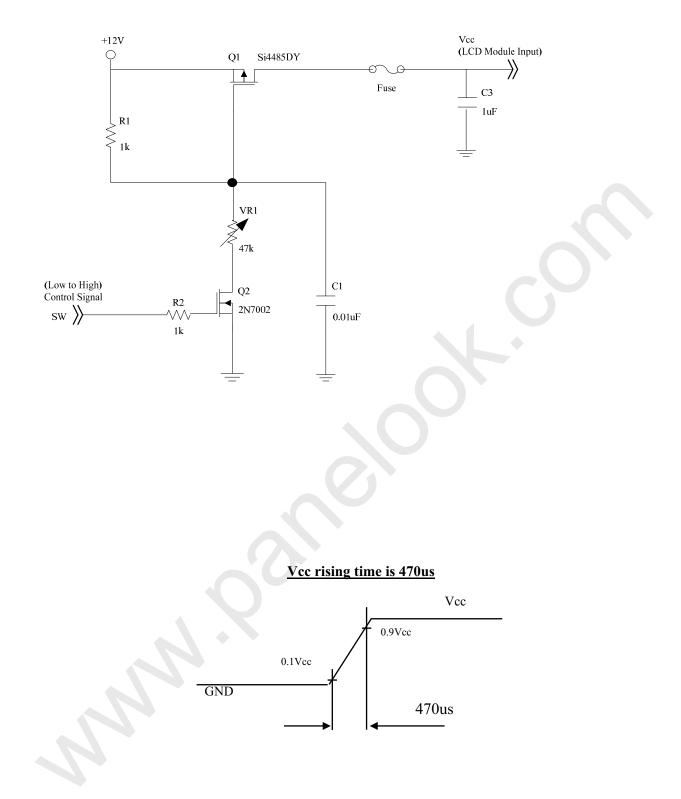
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- Note (3) The Specified Power consumption is under XXX pattern.
- Note (4) The specified power supply current is under the conditions at Vcc =12V, Ta = 25 ± 2 °C, $f_v = 60$ Hz, whereas a power dissipation check pattern below is displayed.

a. White Pattern b. Black Pattern Active Area Active Area c. Horizontal Pattern Note (5) The LVDS input characteristics are as follows: LVDS -Vid LVDS + Vсм GND

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[Vid]

LVDS +/-

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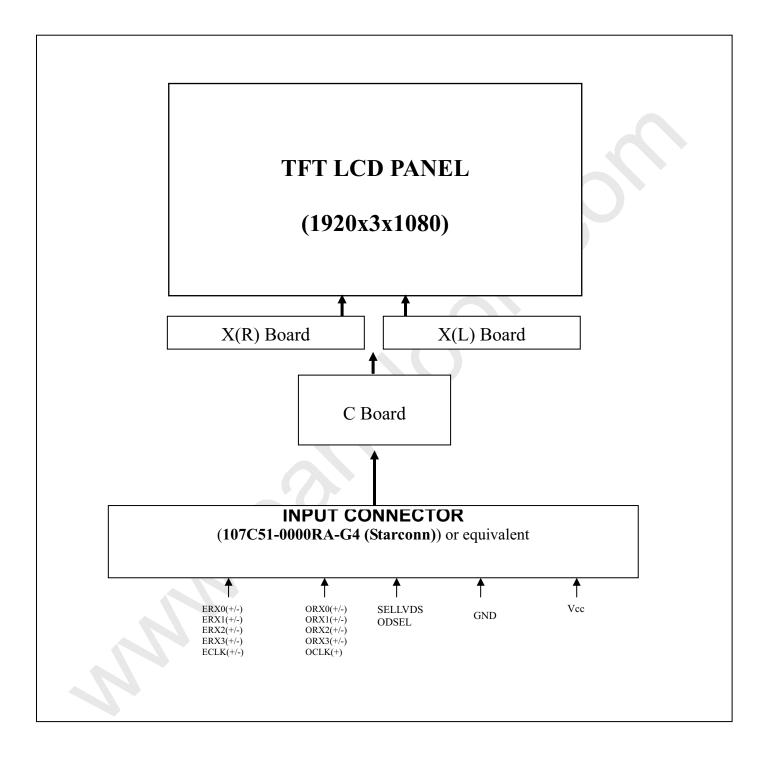
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4. BLOCK DIAGRAM OF INTERFACE

4.1 TFT LCD MODULE



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5. INTERFACE PIN CONNECTION

5.1 TFT LCD MODULE

CNF1 Connector Pin Assignment (107C51-0000RA-G4 (Starconn) or equivalent)

Pin	Name	Description	Note
1	GND	Ground	
2	N.C.	No Connection	
3	N.C.	No Connection	
4	N.C.	No Connection	(2)
5	N.C.	No Connection	
6	N.C.	No Connection	
7	SELLVDS	LVDS data format Selection	(3)(5)
8	N.C.	No Connection	(2)
9	ODSEL	Overdrive Lookup Table Selection	(4)(6)
10	N.C.	No Connection	(2)
11	GND	Ground	
12	ERX0-	Even pixel Negative LVDS differential data input. Channel 0	
13	ERX0+	Even pixel Positive LVDS differential data input. Channel 0	
14	ERX1-	Even pixel Negative LVDS differential data input. Channel 1	(7)
15	ERX1+	Even pixel Positive LVDS differential data input. Channel 1	(7)
16	ERX2-	Even pixel Negative LVDS differential data input. Channel 2	
17	ERX2+	Even pixel Positive LVDS differential data input. Channel 2	
18	GND	Ground	
19	ECLK-	Even pixel Negative LVDS differential clock input.	(7)
20	ECLK+	Even pixel Positive LVDS differential clock input.	(7)
21	GND	Ground	
22	ERX3-	Even pixel Negative LVDS differential data input. Channel 3	(7)
23	ERX3+	Even pixel Positive LVDS differential data input. Channel 3	(7)
24	N.C.	No Connection	(2)
25	N.C.	No Connection	(2)
26	GND	Ground	
27	GND	Ground	
28	ORX0-	Odd pixel Negative LVDS differential data input. Channel 0	
29	ORX0+	Odd pixel Positive LVDS differential data input. Channel 0	
30	ORX1-	Odd pixel Negative LVDS differential data input. Channel 1	
31	ORX1+	Odd pixel Positive LVDS differential data input. Channel 1	(7)
32	ORX2-	Odd pixel Negative LVDS differential data input. Channel 2	
33	ORX2+	Odd pixel Positive LVDS differential data input. Channel 2	

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34	GND	Ground	
35	OCLK-	Odd pixel Negative LVDS differential clock input	(7)
36	OCLK+	Odd pixel Positive LVDS differential clock input	(7)
37	GND	Ground	
38	ORX3-	Odd pixel Negative LVDS differential data input. Channel 3	(7)
39	ORX3+	Odd pixel Positive LVDS differential data input. Channel 3	(7)
40	N.C.	No Connection	(2)
41	N.C.	No Connection	(2)
42	GND	Ground	
43	GND	Ground	
44	GND	Ground	
45	GND	Ground	
46	GND	Ground	
47	N.C.	No Connection	(2)
48	VCC	Power input (+12V)	
49	VCC	Power input (+12V)	
50	VCC	Power input (+12V)	
51	VCC	Power input (+12V)	

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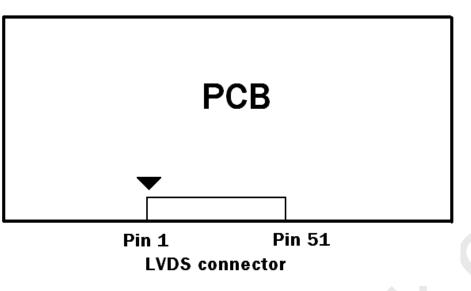
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PRODUCT SPECIFICATION

Note (1) LVDS connector pin order defined as follows



Note (2) Reserved for internal use. Please leave it open.

Note (3) Low = Open or connect to GND: VESA Format, High = Connect to +3.3V: JEIDA Format.

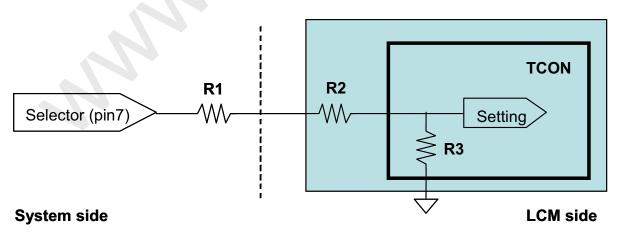
Note (4) Overdrive lookup table selection. The overdrive lookup table should be selected in accordance with

the frame rate to optimize image quality.

Low = Open or connect to GND, High = Connect to +3.3V

ODSEL	Note
L or open	Lookup table was optimized for 60 Hz frame
Н	Lookup table was optimized for 50 Hz frame

Note (5) LVDS signal pin connected to the LCM side has the following diagram. R1 in the system side should be less than 1K Ohm. (R1 < 1K Ohm)

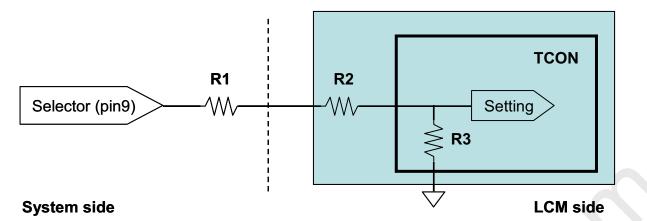


Note (6) ODSEL signal pin connected to the LCM side has the following diagram. R1 in the system side should be less than 1K Ohm. (R1 < 1K Ohm)

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Note (7) Two pixel data send into the module for every clock cycle. The first pixel of the frame is odd pixel and the second pixel is even pixel

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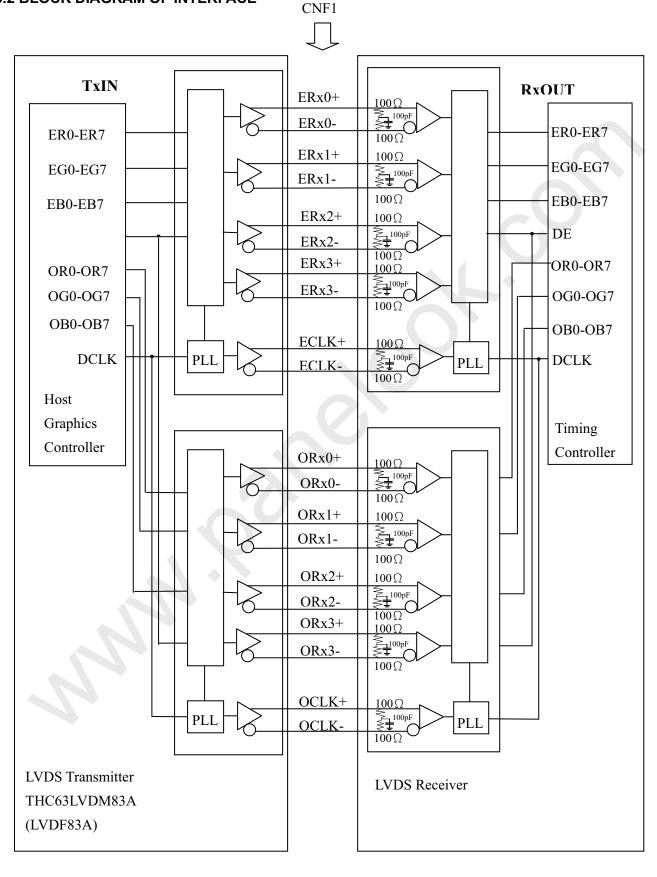


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PRODUCT SPECIFICATION

5.2 BLOCK DIAGRAM OF INTERFACE



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ER0~ER7: Even pixel R data EG0~EG7: Even pixel G data EB0~EB7: Even pixel B data OR0~OR7: Odd pixel R data OG0~OG7: Odd pixel G data OB0~OB7: Odd pixel B data DE: Data enable signal DCLK: Data clock signal

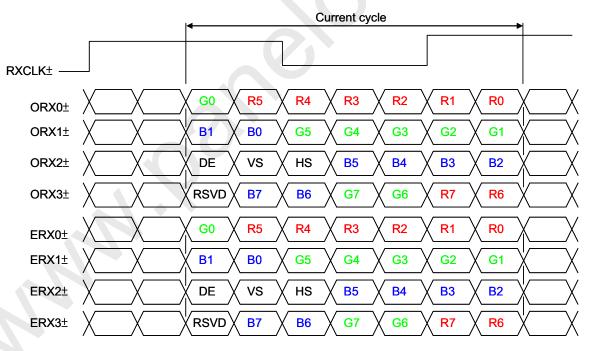
Note (1) The system must have the transmitter to drive the module.

Note (2) LVDS cable impedance shall be 50 ohms per signal line or about 100 ohms per twist-pair line when it is used differentially.

Note (3) Two pixel data send into the module for every clock cycle. The first pixel of the frame is odd pixel and the second pixel is even pixel.

5.3 LVDS INTERFACE

VESA LVDS format : (SELLVDS pin=L or open)



JEDIA LVDS format : (SELLVDS pin=H)

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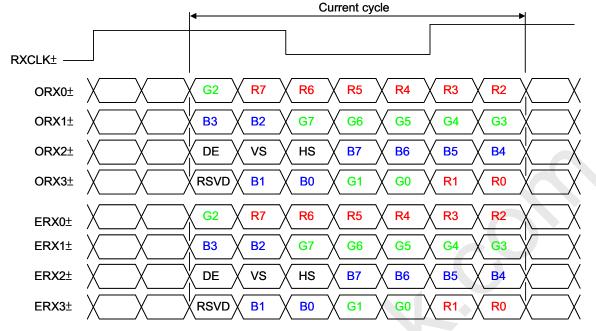
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PRODUCT SPECIFICATION



R0~R7: Pixel R Data (7; MSB, 0; LSB)

G0~G7: Pixel G Data (7; MSB, 0; LSB)

B0~B7: Pixel B Data (7; MSB, 0; LSB)

DE: Data enable signal

DCLK : Data clock signal

Notes: (1) RSVD (reserved) pins on the transmitter shall be "H" or "L".

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PRODUCT SPECIFICATION

5.4 COLOR DATA INPUT ASSIGNMENT

The brightness of each primary color (red, green and blue) is based on the 8-bit gray scale data input for the color. The higher the binary input, the brighter the color. The table below provides the assignment of the color versus data input.

	·											Da	ata	Sigr	nal										
	Color				Re	ed							G	reer	ı						Bl	ue			
	COIOI	R7	R6	R5	R4	R3	R2	R1	R0	G 7	G 6	G 5	G 4	G3	G2	G1	G0	B7	B6	В5	B4	B3	B2	B 1	B0
	Black	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
Basic	Blue	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
Colors	Cyan	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Magenta	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Yellow	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	White	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Red (0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red (1)	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Gray	Red (2)	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Scale	:	:	:	:	:	:	÷	÷	÷	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Red	Red (253)	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Keu	Red (254)	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red (255)	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green (0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green (1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0
Gray	Green (2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0
Scale	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Green	Green (253)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0
Green	Green (254)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0
	Green (255)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	Blue (0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Gray	Blue (1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
Scale	Blue (2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0
Of	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Blue	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:

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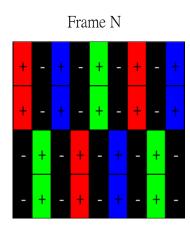
Blue (253)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1
Blue (254)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0
Blue (255)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1

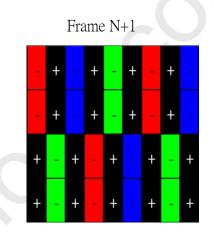
Note (1) 0: Low Level Voltage, 1: High Level Voltage

5.5 FLICKER (Vcom) ADJUSTMENT

(1) Adjustment Pattern:

2n line-inversion pattern was shown as below. If customer need below pattern, please directly contact with Account FAE.





(2) Adjustment method: (Digital V-com)

Programmable memory IC is used for Digital V-com adjustment in this model. CMI provide Auto Vcom tools to adjust Digital V-com. The detail connection and setting instruction, please directly contact with Account FAE to refer CMI Auto V-com adjustment OI. Below items is suggested to be ready before Digital V-com adjustment in customer LCM line.

- a. USB Sensor Board. (CMI Part number: 35-D044998)
- b. Programmable software. (Multi Auto Vcom 1.0.6)
- c. Document: Auto V-com adjustment suggestion OI. (CMI DCC number: 300019662)

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PRODUCT SPECIFICATION

6. INTERFACE TIMING

6.1 INPUT SIGNAL TIMING SPECIFICATIONS

 $(Ta = 25 \pm 2 \ ^{\circ}C)$

The input signal timing specifications are shown as the following table and timing diagram.

1 0				0	0	<u> </u>	
Signal	Item	Symbol	Min.	Тур.	Max.	Unit	Note
LVDS	Frequency	F _{clkin} (=1/TC)	60	74.25	80	MHz	0
	Input cycle to cycle jitter	T _{rcl}	_	_	200	ps	(2)
Receiver Clock	Spread spectrum modulation range	Fclkin_mo d	F _{clkin} -2%	_	F_{clkin} +2%	MHz	
	Spread spectrum modulation frequency	F _{SSM}	_	-	200	KHz	(3)
LVDS	Setup Time	Tlvsu	600		-	ps	
Receiver Data	Hold Time	Tlvhd	600		_	ps	
	Frame Rate	F _{r5}	47	50	53	Hz	
Vertical	Frame Kate	F _{r6}	57	60	63	Hz	
Active Display	Total	Tv	1115	1125	1135	Th	Tv=Tvd+T vb
Term	Display	Tvd	1080	1080	1080	Th	
	Blank	Tvb	35	45	55	Th	
Horizontal Active	Total	Th	1050	1100	1150	Тс	Th=Thd+T hb
Display	Display	Thd	960	960	960	Tc	
Term	Blank	Thb	90	140	190	Tc	
			90	140	190	Тс	

Note (1) Please make sure the range of frame rate has follow the below equation :

 $Fr(max) \ge Fclkin / Tv \times Th \le Fr(min)$

Note (2) The input clock cycle-to-cycle jitter is defined as below figures. Trcl = I T_1 – TI

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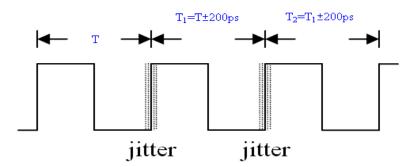
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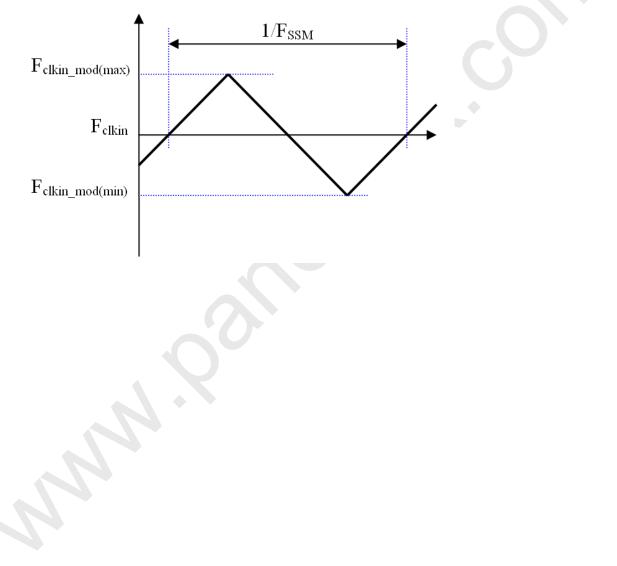




PRODUCT SPECIFICATION



Note (3) The SSCG (Spread spectrum clock generator) is defined as below figures.



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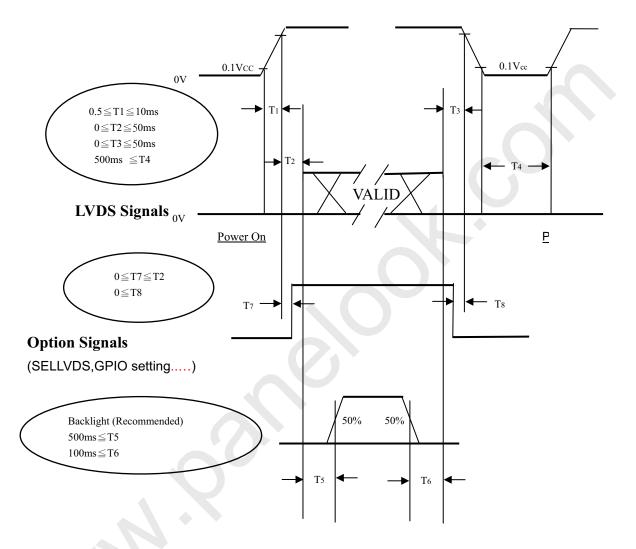


PRODUCT SPECIFICATION

6.2 POWER ON/OFF SEQUENCE

 $(Ta = 25 \pm 2 \ ^{\circ}C)$

To prevent a latch-up or DC operation of LCD module, the power on/off sequence should be as the diagram below.



Power ON/OFF Sequence

Note (1) The supply voltage of the external system for the module input should follow the definition of Vcc. Note (2) Apply the lamp voltage within the LCD operation range. When the backlight turns on before the LCD operation or the LCD turns off before the backlight turns off, the display may momentarily become abnormal screen. Note (3) In case of VCC is in off level, please keep the level of input signals on the low or high impedance. Note (4) T4 should be measured after the module has been fully discharged between power off and on period. Note (5) Interface signal shall not be kept at high impedance when the power is on.

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PRODUCT SPECIFICATION

7. OPTICAL CHARACTERISTICS

7.1 TEST CONDITIONS

The LCD module should be stabilized at given temperature for 1 hour to avoid abrupt temperature change during

measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 1

hour in a windless room.

Item	Symbol	Value	Unit
Ambient Temperature	Та	25±2	°C
Ambient Humidity	На	50±10	%RH
Supply Voltage	V _{CC}	12	V
Input Signal	According to typical value	e in "3. ELECTRICAL CH	ARACTERISTICS"
Vertical Frame Rate	Fr	60	Hz

7.2 OPTICAL SPECIFICATIONS

The relative measurement methods of optical characteristics are shown in 7.2. The following items should be measured under the test conditions described in 7.1 and stable environment shown in 7.1.

Iten	n	Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Contrast Ratio		CR		2000	3000	-	-	(2), (4)
Response Time		Gray to gray	θ _x =0°, θ _Y =0°		8.5	17	ms	(5)
Center Transmit	tance	Т%	With CMI Module		4.8	-	%	(2), (8)
White Variation		δW		-	-	1.3	-	(2), (7)
	Red	Rcx			0.658		-	
	Reu	Rcy			0.324	_	-	
	Green	Gcx			0.257		-	
Color		Gcy	θ _x =0°, θ _Y =0° CS-2000	Тур -	0.593	Typ +	-	(1) (6)
Chromaticity	Blue	Bcx	Standard light source "C	0.03	0.135	0.03	-	(1),(6)
		Всу	Standard light source C		0.096		-	
	White	Wcx			0.295		-	
	White	Wcy			0.337		-	
	Horizontal	θ_{x} +		80	88	-		
	rionzoniai	θ _x -	CR≥20	80	88	-	Dog	(2) (2)
Viewing Angle	Vertical	θ_{Y} +	With CMI Module	80	88	-	Deg.	(2), (3)
	Vertical	θγ-		80	88	-		

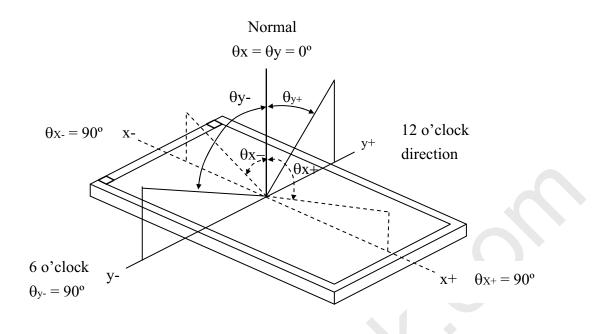
Note (1) Light source is the standard light source "C" which is defined by CIE and driving voltages are based on suitable gamma voltages. The calculating method is as following :

- 1. Measure Module's and BLU's spectrums. W, R, G, B are with signal input. BLU(for V420H2_LE5) is supplied by CMI.
- 2. Calculate cell's spectrum.
- 3. Calculate cell's chromaticity by using the spectrum of standard light source "C"
- Note (2) Light source is the BLU which is supplied by CMI and driving voltages are based on suitable gamma voltages.
- Note (3) Definition of Viewing Angle (θx , θy):

Viewing angles are measured by Conoscope Cono-80 (or Eldim EZ-Contrast 160R)

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Note (4) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

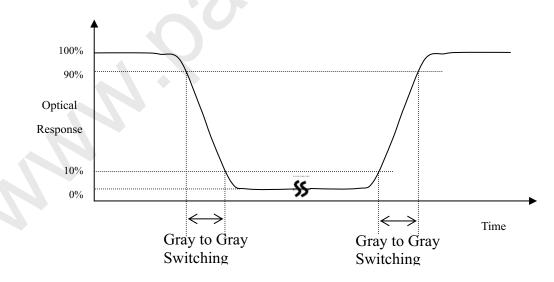
Contrast Ratio (CR) = L255 / L0

L 255: Luminance of gray level 255

L 0: Luminance of gray level 0

CR = CR (1), where CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note (7).

Note (5) Definition of Gray to Gray Switching Time:



The driving signal means the signal of gray level 0, 124, 252, 380, 508, 636, 764, 892 and 1023. Gray to gray average time means the average switching time of gray level 0, 124, 252, 380, 508,636, 764, 892 and 1023.

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		A (1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	

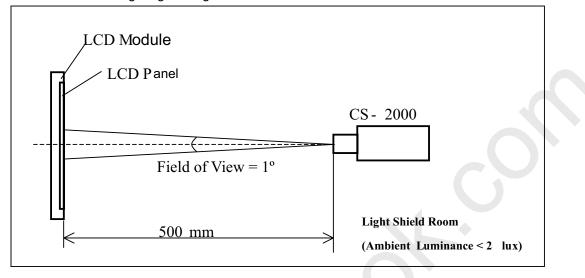
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Note (6) Measurement Setup:

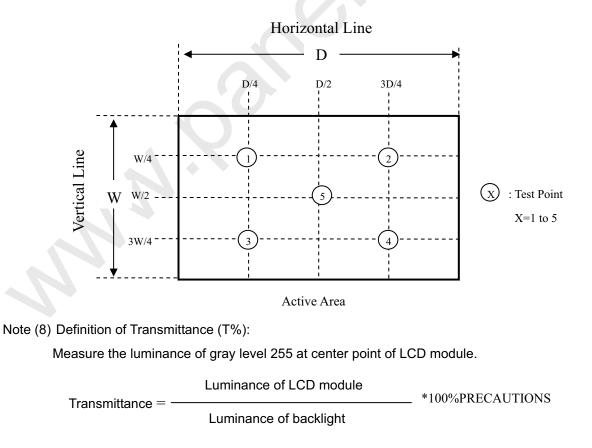
The LCD module should be stabilized at given temperature for 1 hour to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 1 hour in a windless room.



Note (7) Definition of White Variation (δW):

Measure the luminance of gray level 255 at 5 points

δW = Maximum [L (1), L (2), L (3), L (4), L (5)] / Minimum [L (1), L (2), L (3), L (4), L (5)]



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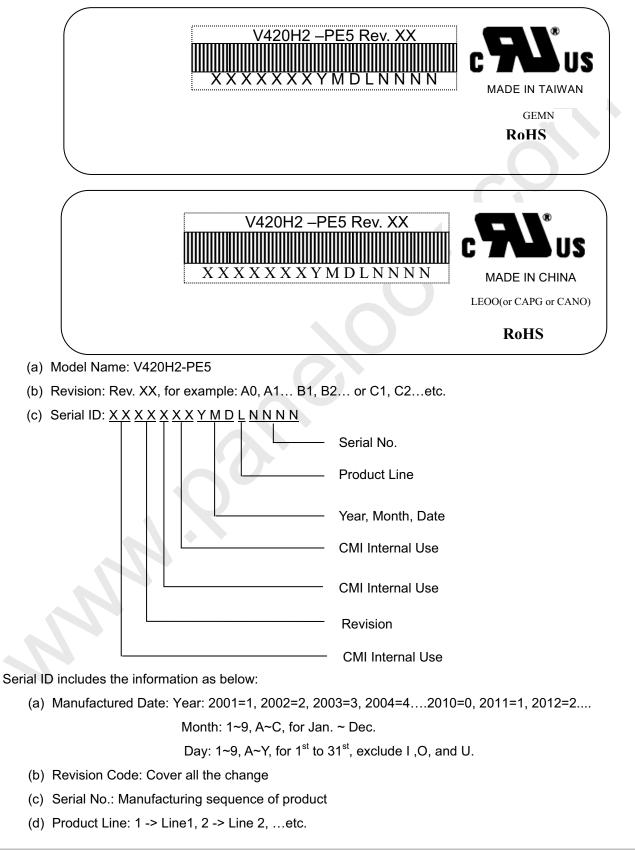


PRODUCT SPECIFICATION

8. DEFINITION OF LABELS

8.1 CMI MODULE LABEL

The barcode nameplate is pasted on each module as illustration, and its definitions are as following explanation.



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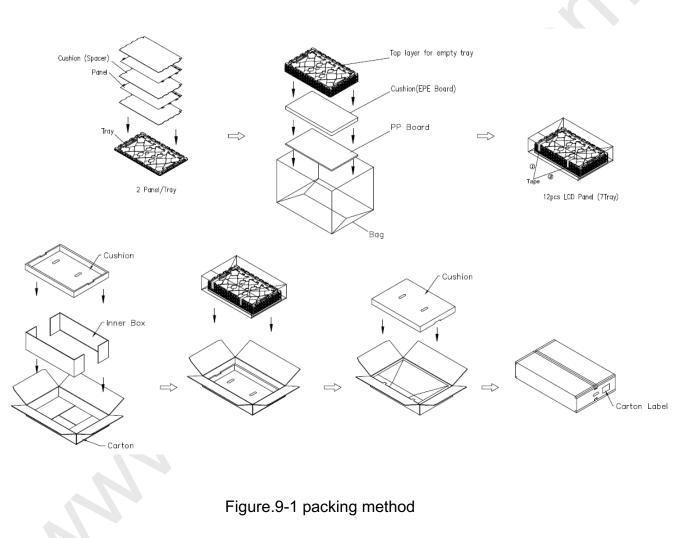
9. PACKAGING

9.1 PACKING SPECIFICATIONS

- (1) 12PCS LCD TV Panels / 1 Box
- (2) Box dimensions : 1123 (L) X 818 (W) X 245 (H)
- (3) Weight : approximately 43 Kg

9.2 PACKING METHOD

Figures 9-1 and 9-2 are the packing method



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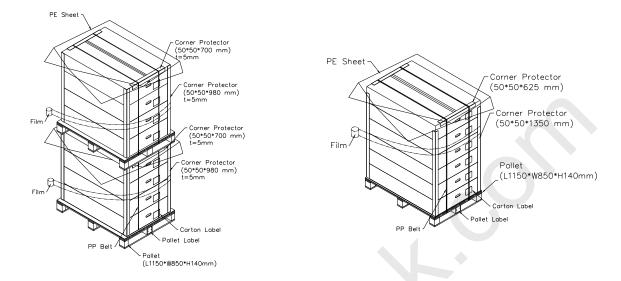
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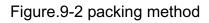


PRODUCT SPECIFICATION

Sea & Land Transportation

Air Transportation





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10. PRECAUTIONS

10.1 ASSEMBLY AND HANDLING PRECAUTIONS

- [1] Do not apply rough force such as bending or twisting to the module during assembly.
- [2] It is recommended to assemble or to install a module into the user's system in clean working areas. The dust and oil may cause electrical short or worsen the polarizer.
- [3] Do not apply pressure or impulse to the module to prevent the damage of LCD panel and Backlight.
- [4] Always follow the correct power-on sequence when the LCD module is turned on. This can prevent the damage and latch-up of the CMOS LSI chips.
- [5] The distance between COF edge and rib of BLU must bigger than 5mm. This can prevent the damage of COF when assemble the module.
- [6] Do not design sharp-pointed structure / parting line / tooling gate on the COF position of plastic parts, because the burr will scrape the COF.
- [7] If COF would bended to assemble in the module. Do not put the IC location on the bending corner of COF.
- [8] The gap between COF IC and any structure of BLU must bigger than 2mm. This can prevent the damage of COF IC
- [9] Bezel opening must have no burr. Burr will scrape the panel surface.
- [10] Bezel of module and bezel of set can not press or touch the panel surface. It will make light leakage or scrape.
- [11] When module used FFC / FPC, but no FFC / FPC to be attached in the open cell. Customer can refer the FFC / FPC drawing and buy it by self.
- [12] The gap between Panel and any structure of Bezel must bigger than 2mm. This can prevent the damage of Panel.
- [13] Do not plug in or pull out the I/F connector while the module is in operation.
- [14] Do not disassemble the module.
- [15] Use a soft dry cloth without chemicals for cleaning, because the surface of polarizer is very soft and easily scratched.
- [16] Moisture can easily penetrate into LCD module and may cause the damage during operation.
- [17] When storing modules as spares for a long time, the following precaution is necessary.
 - [17.1] Do not leave the module in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35°C at normal humidity without condensation.
 - [17.2] The module shall be stored in dark place. Do not store the TFT-LCD module in direct sunlight or fluorescent light.
- [18] When ambient temperature is lower than 10°C, the display quality might be reduced.

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10.2 SAFETY PRECAUTIONS

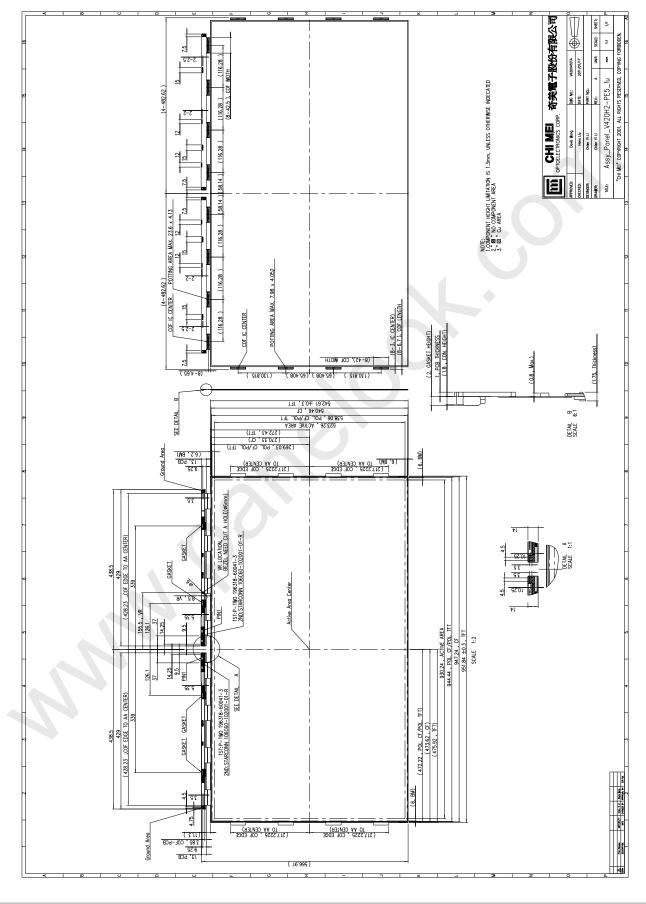
- (1) The startup voltage of a Backlight is approximately 1000 Volts. It may cause an electrical shock while assembling with the inverter. Do not disassemble the module or insert anything into the Backlight unit.
- [2] If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, skin or clothes, it has to be washed away thoroughly with soap.
- [3] After the module's end of life, it is not harmful in case of normal operation and storage.

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11. MECHANICAL CHARACTERISTICS



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